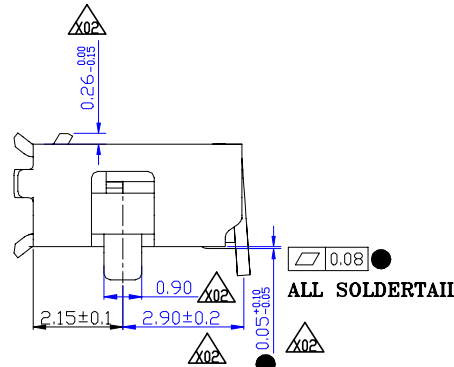
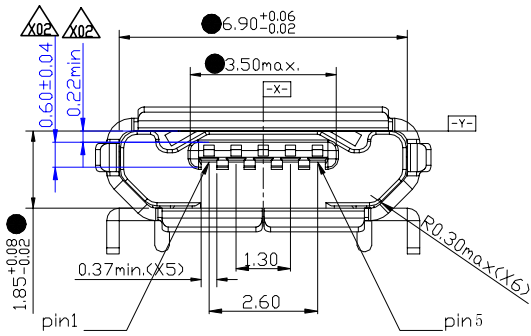
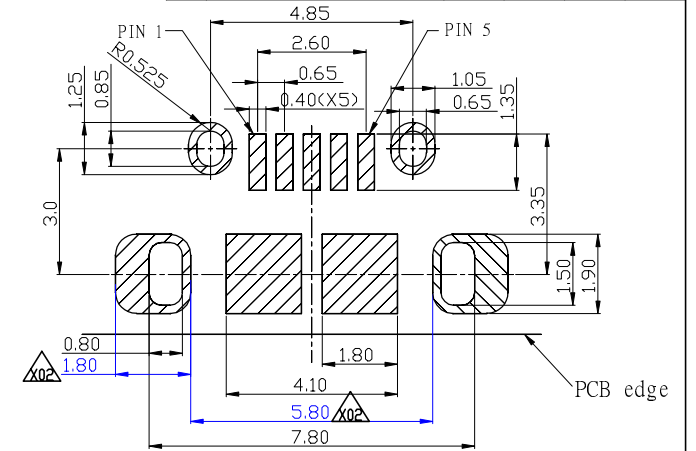
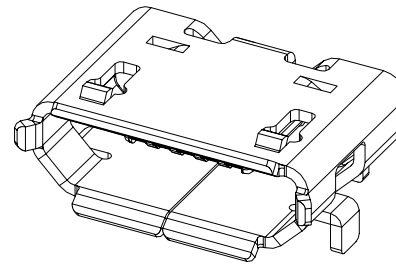
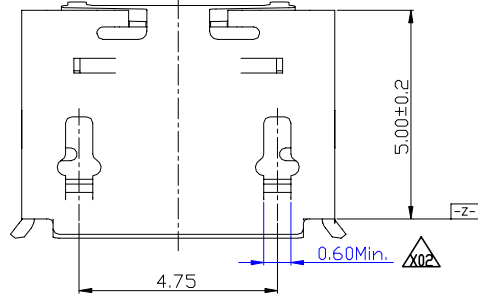


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CAD FILE: XS05112-01A

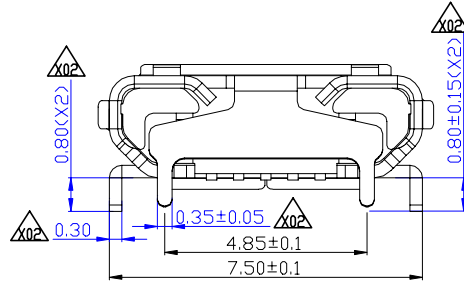
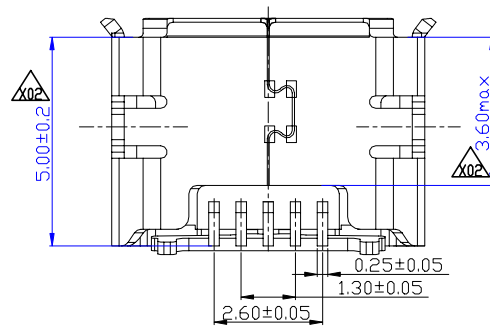
REV.	DESCRIPTION	DWG		APPROVED	
		NAME	DATE	NAME	DATE
X01	PROTOTYPE	Roger	12/30/2009	Knight	12/30/2009
X02	UPDATE DRAWING	Roger	01/13/2010	Knight	01/13/2010

- 1 ■ Functionally dim.
- ◆ Assembly dim.
- Control dim.



Note:

1. Material
  - Housing: Heat temperature thermoplastic black UL94 V-0
  - △X02 Contact: Copper Alloy T=0.15mm  
Ni under plating, Gold flash on solder area  
Au 10u" plating on contact area
  - Shell: Stainless Steel T=0.30mm
  - △X02 Matte Tin 150u"Min. Over Nickle 50u" Min.
2. Electrical Specification
  - Contact Resistance: Initial: 30mΩ Max.  
After Duribility: Change(delta) of +10 mΩ
  - Isulation Resistance: Initial: 100MΩ Min.  
After testing: 100MΩ Min.
  - Dielectric withstanding Voltage: 100V AC for one minute
3. Mechanical Specification
  - Mating Force: Initial: 35N Max.  
After duribility: 35N Max.
  - Unmating Force: Initial: 8N Min.  
After duribility: 8N Min.
  - Duribility: 10000 cycle



Back View

<b>INTENDED USE:</b> ACT		<b>Advanced Connection Technology</b> TAIWAN TEL: 886-2-88091060			
<b>GENERAL DIMENSION</b>		TITLE: <b>Micro USB B Type I/O</b>		DRAWN: <b>Roger</b> 12/30/2009	
XX±0.30	.X±0.20	<b>NORMAL DIP 0.8mm</b>		CHECKED:	
X±0.25	.XX±0.10	DWG NO: <b>305-05112-01</b>		REV. <b>X02</b> 12/30/2009	
		APPROVED: <b>Knight</b> 12/30/2009		NAME DATE	
UNIT: <b>mm</b>	SCALE: <b>NONE</b>	SHEET <b>1 OF 1</b>			